

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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31-01/B4C-AKNB

Features

- . High Flux Output.
- . Low Profile.
- . Low Thermal Resistance.
- . Low Power Consumption.
- .The product itself will remain within RoHS compliant version.
- . ESD-withstand voltage: up to 4KV.



Descriptions

This revolutionary package design allows the light designer to reduce the number of LEDs required and provide a more uniform and unique illuminated appearance than with other LED solutions. This is possible through the efficient optical package design and high-current capabilities.

The low profile package can be easily coupled with reflectors or lenses to efficiently distribute light and provide the desired light appearance.

Applications

- . Automotive Exterior Lighting
- . Electronic Signs and Signals
- . Channel Letter
- . Special Lighting application

Device Selection Guide

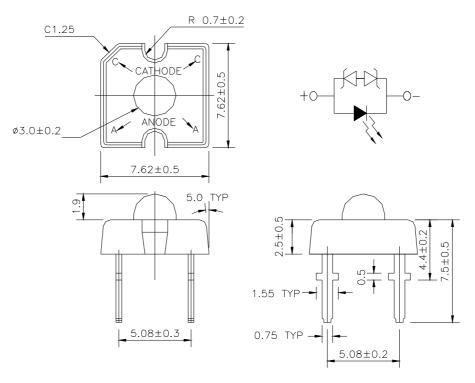
	C		
PART NO.	Material	Emitted Color	Lens Color
31-01/B4C-AKNB	InGaN	Blue	Water Clear

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Package Dimensions



Notes: 1.All dimensions are in millimeters

- 2.An epoxy meniscus may extend about 1.5mm(0.059") down the leads
- 3. Tolerances unless dimensions ±0.25mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Units
Continuous Forward Current	$ m I_F$	30	mA
Peak Forward Current(Duty 1/10 @ 1KHZ)	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}\!\mathbb{C}$
Soldering Temperature(T=5 sec)	T_{sol}	260	$^{\circ}\!\mathbb{C}$
Power Dissipation	P _d	120	mW
Zener Reverse Current	Iz	100	mA
Electrostatic Discharge	ESD	4K	V

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Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Тур.	Max.	Condition	Unit
Total Flux	Фу	1125		2850	I _F =30mA	mlm
Viewing Angle	2 θ 1/2		50		I _F =30mA	deg
Peak Wavelength	λр		468		I _F =30mA	Nm
Dominant Wavelength	λd	464	470	476	I _F =30mA	Nm
Spectrum Radiation Bandwidth	Δλ		35		I _F =30mA	nm
Forward Voltage	VF	2.8	3.5	3.8	I _F =30mA	V
Reverse Current	IR			10	V _R =5V	uA
Zener Reverse Voltage	Vz	5.2			Iz=5mA	V

Rank

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(1)

(2)

(3)

	(1) VF(V)		(2) λd		$(3)\Phi v(mlm)$			
Bin.	Min.	Max.	Bin.	Min.	Max.	Bin.	Min.	Max.
0	2.80	3.00	3	464	468	K	1125	1425
1	3.00	3.20	4	468	472	L	1425	1800
2	3.20	3.40	5	472	476	M	1800	2250
3	3.40	3.60				N	2250	2850
4	3.60	3.80						

^{*}Measurement Uncertainty of Forward Voltage : $\pm 0.1 V$

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^{*}Measurement Uncertainty of Total Flux: ±15%

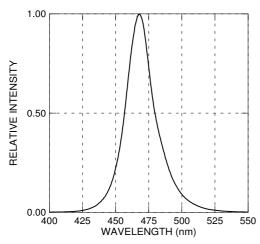
^{*}Measurement Uncertainty of Dominant Wavelength: ±1.0nm



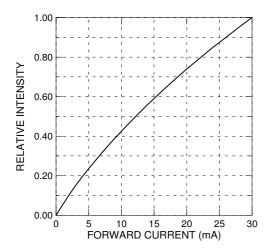
31-01/B4C-AKNB

Typical Electro-Optical Characteristics Curves

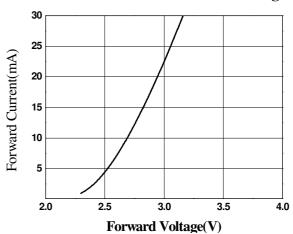
Relative Intensity vs. Wavelength



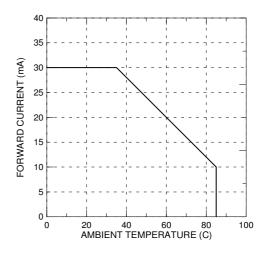
Relative Intensity vs. Forward Current



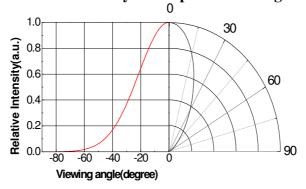
Forward Current vs. Forward Voltage



Forward Current vs. Ambient Temp.



Relative Intensity vs. Displacement Angle



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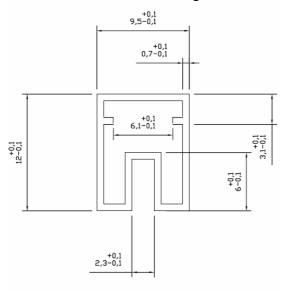


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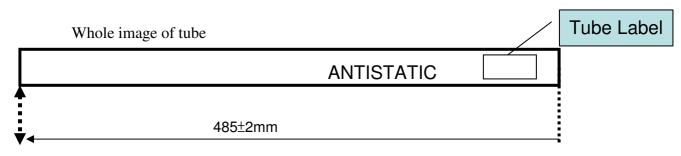
Packing Specification

1. Tube

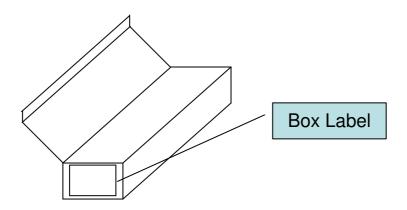
Cross section image of tube



Unit: mm



2. Inner Box



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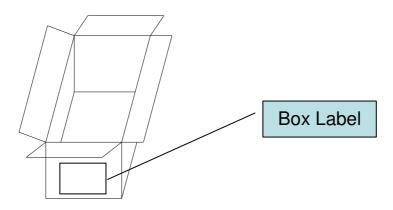
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3. Outside Box

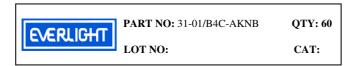


Packing Quantity Specification

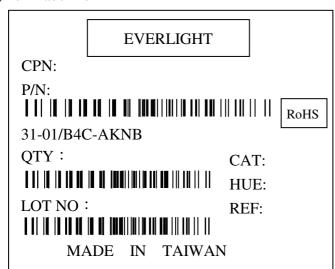
- (1) 60 pcs/1 tube, 30 tubes/1 small inside box, 12 small inside boxes/1 outside box
- (2) 60 pcs/1 tube, 105 tubes/1 big inside box, 4 big inside boxes/1 outside box

Label Form Specification

(1)Tube Label Form



(2)Box Label Form



PART NO: Everlgiht's Production Number

QTY: Packing Quantity LOT NO: Lot Number

CAT: Ranks of Forward Voltage, Color Bin Grade and Total Flux

CPN: Customer's Production Number

P/N : Production Number

HUE: Reference REF: Reference

MADE IN TAIWAN: Production Place

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Notes

Lead Forming

- During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
- Lead forming should be done before soldering.
- Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the LEDs.
- When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

2. Storage

- The LEDs should be stored at 30°C or less and 70%RH or less after being shipped from Everlight and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

3. Soldering

- Careful attention should be paid during soldering. Solder the LED no lower than 1.6mm from the base of stopper is recommended.
- Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.

Recommended soldering conditions:

Hand Soldering		DIP Soldering		
Temp. at tip of iron	300°C Max. (30W Max.)	Preheat temp.	100°C Max. (60 sec Max.)	
Soldering time	3 sec Max.	Bath temp.	260 Max.	
Distance	No lower than 1.6mm from	Bath time.	5 sec Max.	
	the base of stopper			
		Distance	No lower than 1.6mm from	
			the base of stopper	

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- Dip and hand soldering should not be done more than one time.
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- Although the recommended soldering conditions are specified in the above table, dip or handsoldering at the lowest possible temperature is desirable for the LEDs.
- Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

4. Cleaning

- When necessary, cleaning should occur only with isopropyl alcohol at room temperature for a duration of no more than one minute. Dry at room temperature before use.
- Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Ultrasonic cleaning shall be pre-qualified to ensure this will not cause damage to the LED

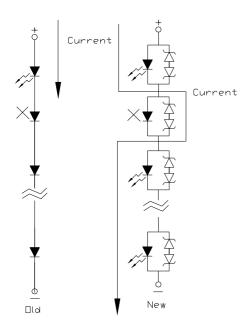
5. Circuit Protection

- Below the zener reference voltage Vz, all the current flows through LED and as the voltage rises to Vz, the zener diode "breakdown." If the voltage tries to rise above Vz current flows through the zener branch to keep the voltage at exactly Vz.
- When the LED is connected using serial circuit, if either piece of LED is no light up but current can't flow through causing others to light down. In new design, the LED is parallel with zener diode. if either piece of LED is no light up but current can flow through causing others to light up.

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6. Heat Management

- Heat management of LEDs must be taken into consideration during the design stage of LED application. The current should be de-rated appropriately by referring to the de-rating curve found in each product specification.
- The temperature surrounding the LED in the application should be controlled. Please refer to the data sheet de-rating curve.

7. ESD (Electrostatic Discharge)

- Electrostatic discharge (ESD) or surge current (EOS) can damage LEDs.
- An ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling LEDs.
- All devices, equipment and machinery must be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing.

8. Other

- Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for

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- any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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